

Improving Bondline Time of Flight Predictions Utilizing Machine Learning and Hardware Improvements

Finnian Day

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Advanced Materials and Processing Branch
NASA Langley Research Center



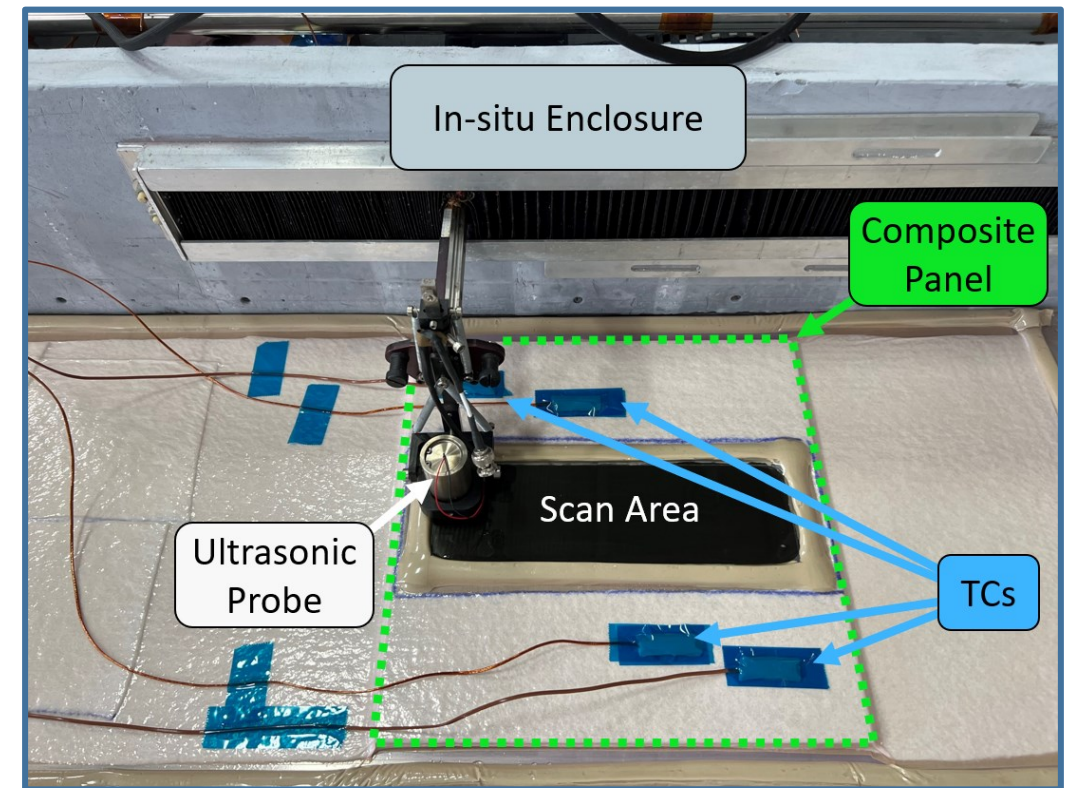


Background

- ❖ Transformational Tools and Technologies (TTT) project aims to develop computational and experimental ways to help predict future aircraft performance
 - ❖ TTT bonded composites team develops tools and methods to analyze and qualify bonded composite joints
 - ❖ Process monitoring subgroup utilizes ultrasonic non-destructive evaluation (NDE) methods to investigate bonded composite joints during cure cycles

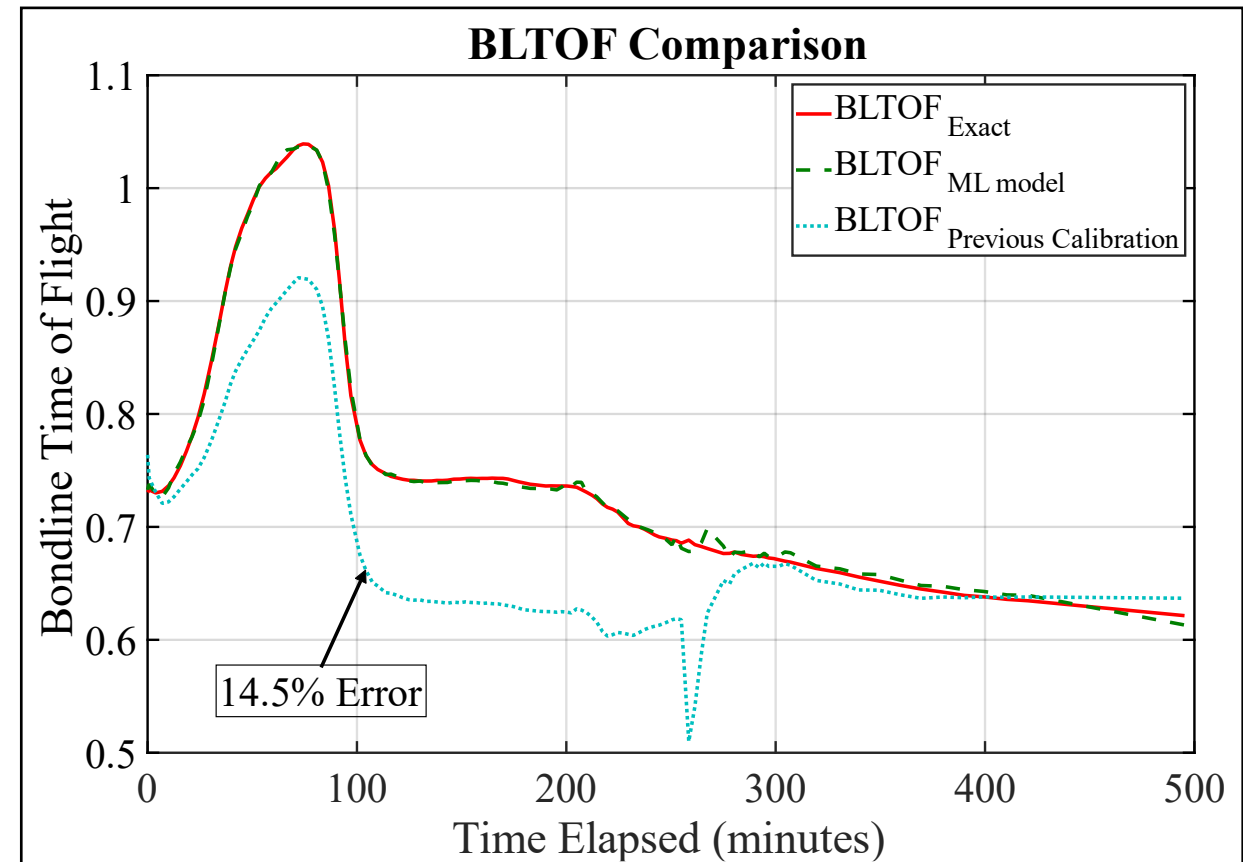
Approach

- ❖ Goal: Measure bondline thickness in composite joints
 - ❖ Strength of bonded joints are related to the thickness of the joint
- ❖ Methods:
 - ❖ In-situ autoclave ultrasonic scanner
 - ❖ 2.25 MHz contact transducer
 - ❖ 10 MHz immersion transducer
 - ❖ Machine learning predictions
- ❖ Challenge:
 - ❖ No commercial system capable of measuring bondline thickness during cure
 - ❖ Measurement error more pronounced in thin materials



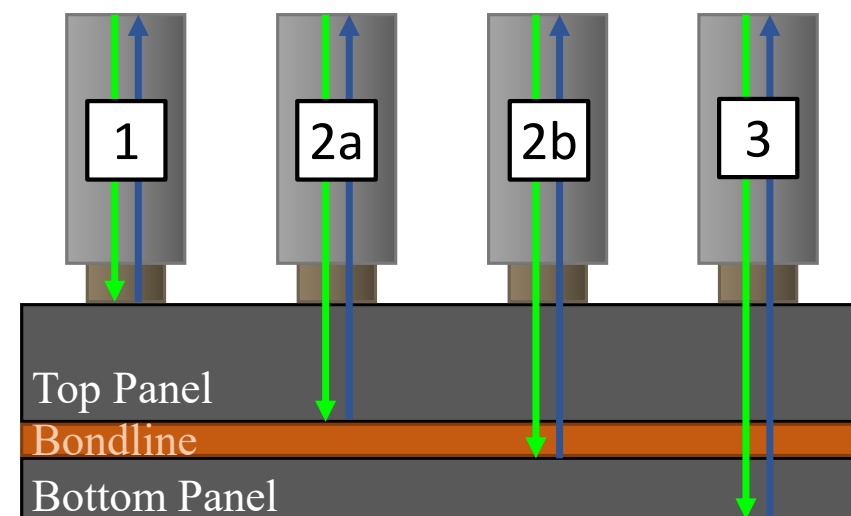
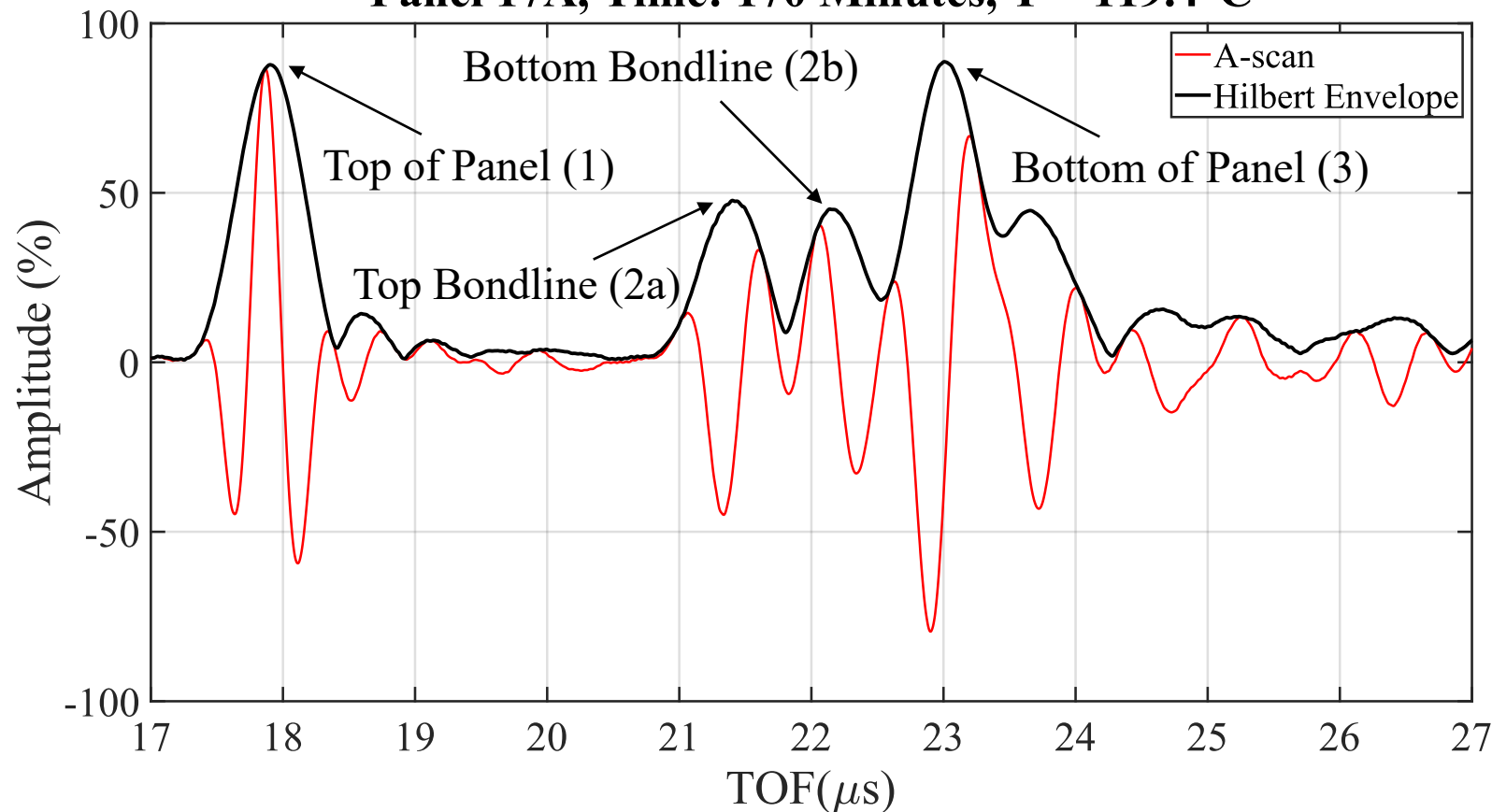
Significance

- ❖ Bondline measured to be about 0.683mm
 - ❖ 14.5% error is roughly 0.1mm
- ❖ 0.1mm error is much more significant with films as thin as the bondline
 - ❖ Less significant for measurements of greater magnitudes



Example Waveform: Glassy State at Cure Temperature

Panel 17A, Time: 170 Minutes, T = 119.4°C

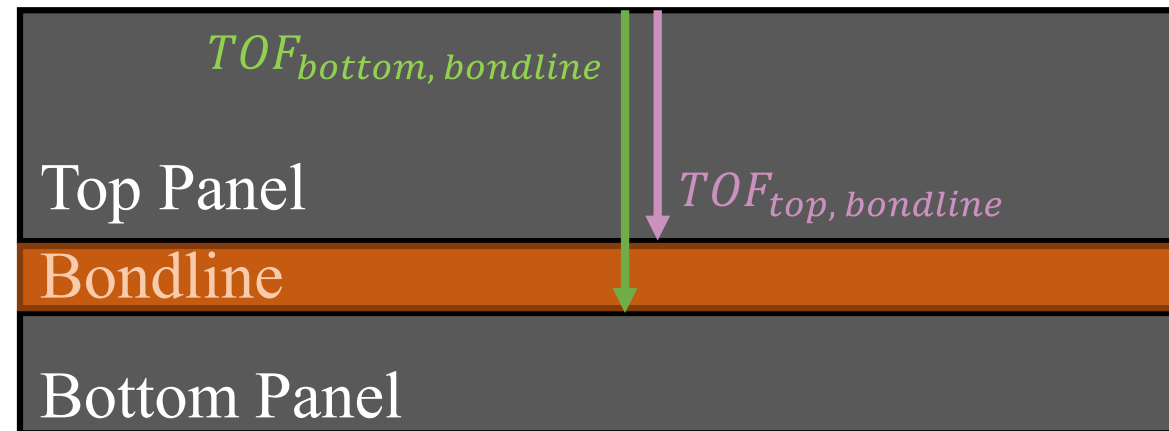


TOF: Direct Method

$$TOF_{bondline} = TOF_{bottom, bondline} - TOF_{top, bondline}$$

$$TOF_{bondline} = TOF_4 - TOF_3$$

- ❖ Provides the most accurate BLTOF measurement
- ❖ Easiest method with clear pulses
 - ❖ More difficult/impossible with thin bondlines
 - ❖ Uncertain top/bottom of bondline



TOF_1

TOF_3

TOF_4

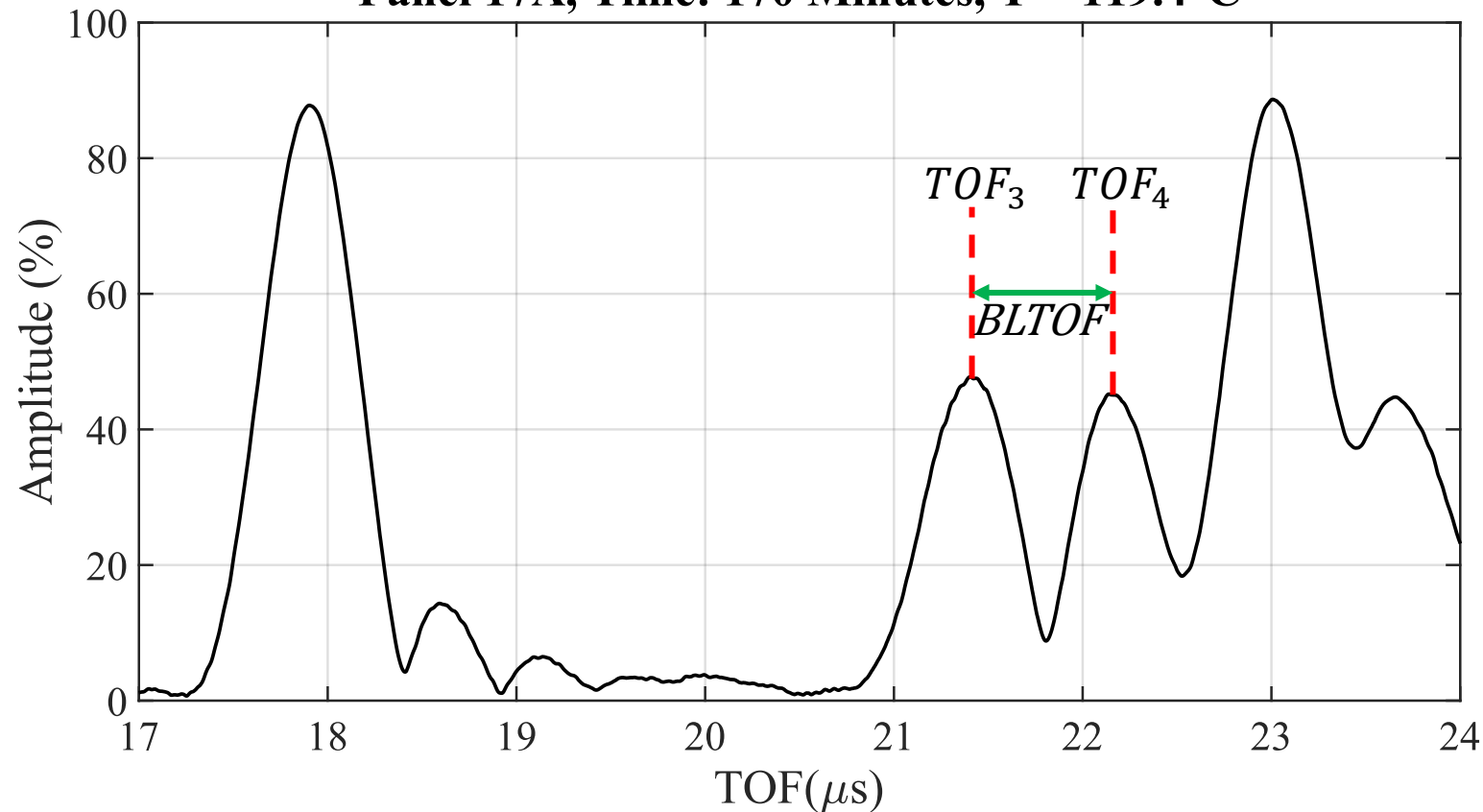
TOF_2

TOF: Direct Method

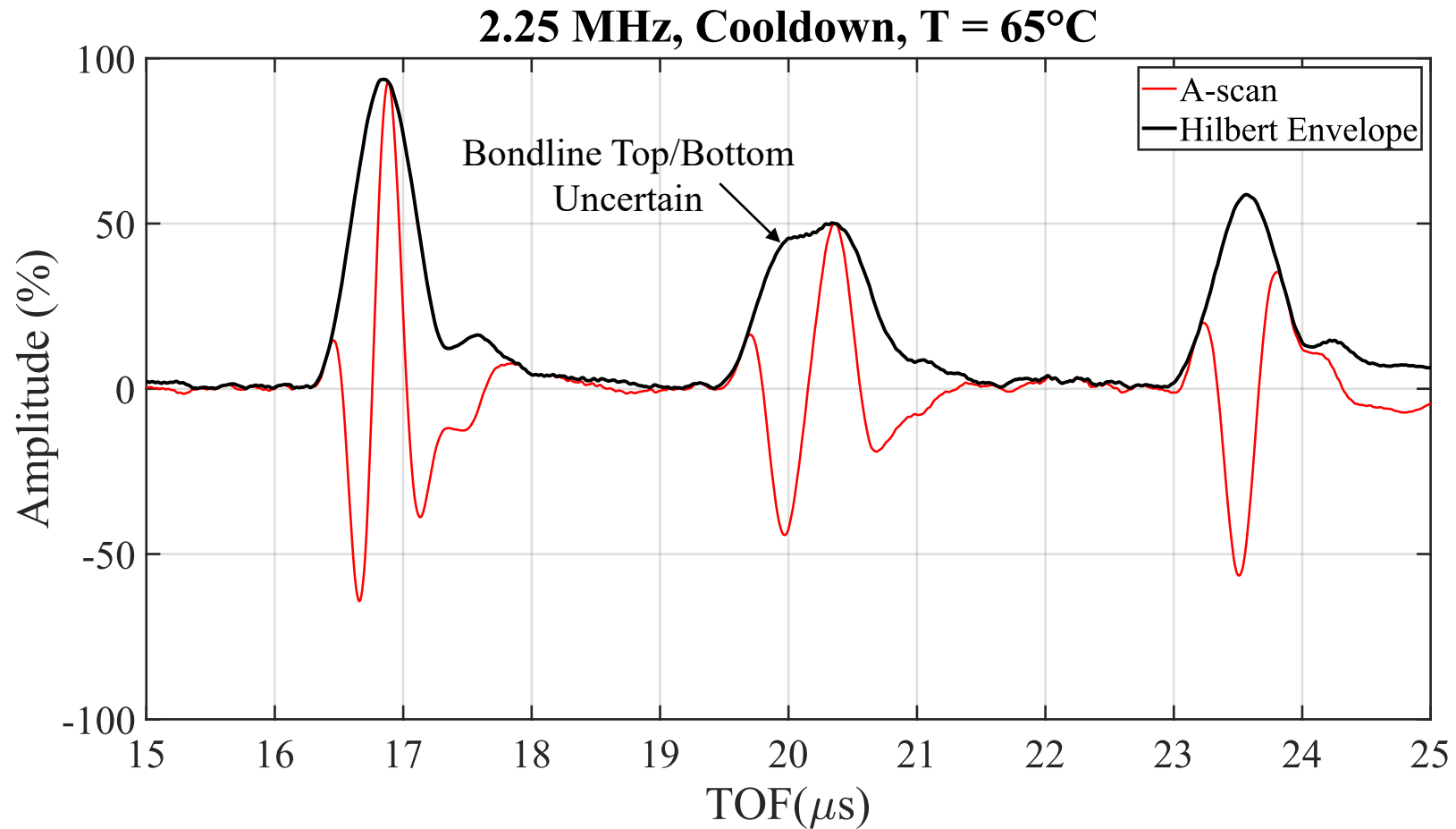
$$TOF_{bondline} = TOF_{bottom, bondline} - TOF_{top, bondline}$$

$$TOF_{bondline} = TOF_4 - TOF_3$$

Panel 17A, Time: 170 Minutes, T = 119.4°C



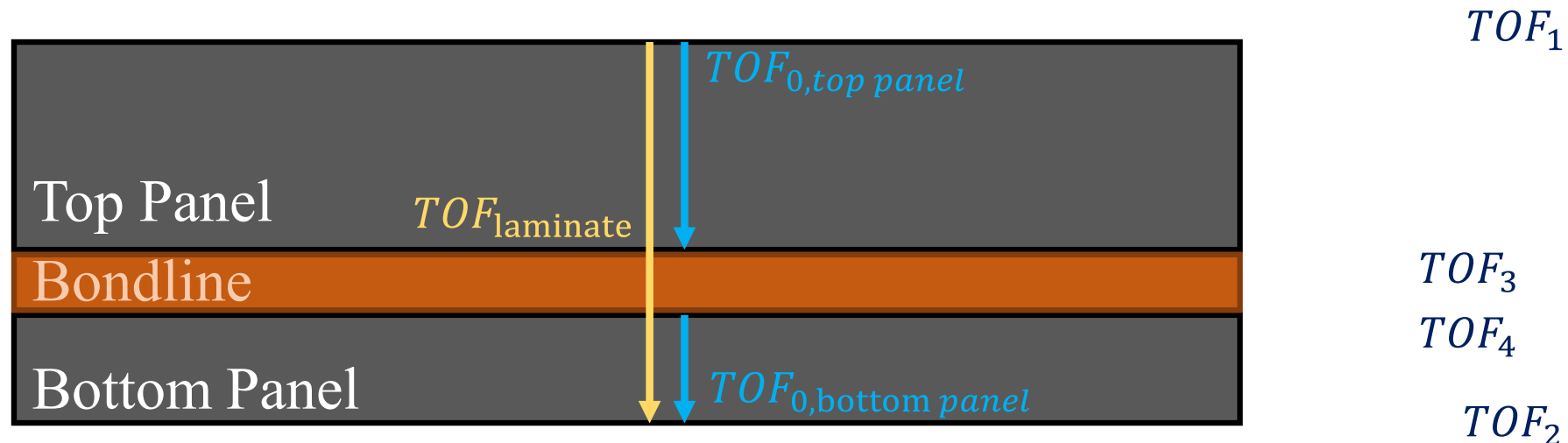
Uncertain Bondline



TOF: Subtraction Method

$$TOF_{bondline} = TOF_{laminates} - TTCF \times (TOF_{0,top\ panel} + TOF_{0,bottom\ panel})$$

- ❖ Top and bottom panels scanned individually without adhesive
- ❖ Subtracted from TOF through entire laminate
- ❖ Temperature directly influences the speed of sound through the half panels
 - ❖ Needs to be corrected for TOF calculations during cure → **TTCF**





TOF Temperature Correction Factor

- ❖ Originally estimated by scanning a cured half panel during full autoclave cycle

- ❖ Found a “multiplier:” $TTCF = \frac{TOF}{TOF_0}$

- ❖ $TTCF(T, P, \dot{T})$ determined using basic regression analysis (i.e., piece-wise curve fitting)



- ❖ “Exact” calculation combines the direct and subtraction methods

- ❖ $TOF_4 - TOF_3 \approx TOF_{laminates} - TTCF \times (TOF_{0,top\ panel} + TOF_{0,bottom\ panel})$

- ❖ $TTCF = \frac{(TOF_2 - TOF_1) - (TOF_4 - TOF_3)}{(TOF_{0,top\ panel} + TOF_{0,bottom\ panel})}$

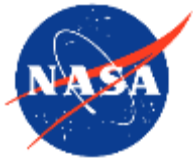
- ❖ Machine learning model fits data to find $TTCF(T, P, \dot{T})$
 - ❖ Model chosen: Support vector machine (SVM) model with fine Gaussian kernel

T : Temperature [°C]

P : Pressure [kPa]

\dot{T} : Ramp Rate [°C/min] 10

Machine Learning Model Selection



	Model Type	RMSE (Test)
1	Gaussian Process Regression (<i>Exponential GPR</i>)	0.00124
2	Gaussian Process Regression (<i>Rational Quadratic GPR</i>)	0.00124
3	Gaussian Process Regression (<i>Matern 5/2 GPR</i>)	0.00162
4	Tree (<i>Fine Tree</i>)	0.00169
5	Gaussian Process Regression (<i>Squared Exponential GPR</i>)	0.00173
6	Ensemble (<i>Bagged Trees</i>)	0.00188
7	Neural Network (<i>Wide Neural Network</i>)	0.00211
8	Tree (<i>Medium Tree</i>)	0.00219
9	Neural Network (<i>Medium Neural Network</i>)	0.00230
10	Neural Network (<i>Trilayered Neural Network</i>)	0.00232
11	Support Vector Machine (<i>Fine Gaussian SVM</i>)	0.00233
12	Neural Network (<i>Bilayered Neural Network</i>)	0.00233
13	Tree (<i>Coarse Tree</i>)	0.00283
14	SVM (<i>Medium Gaussian SVM</i>)	0.00317

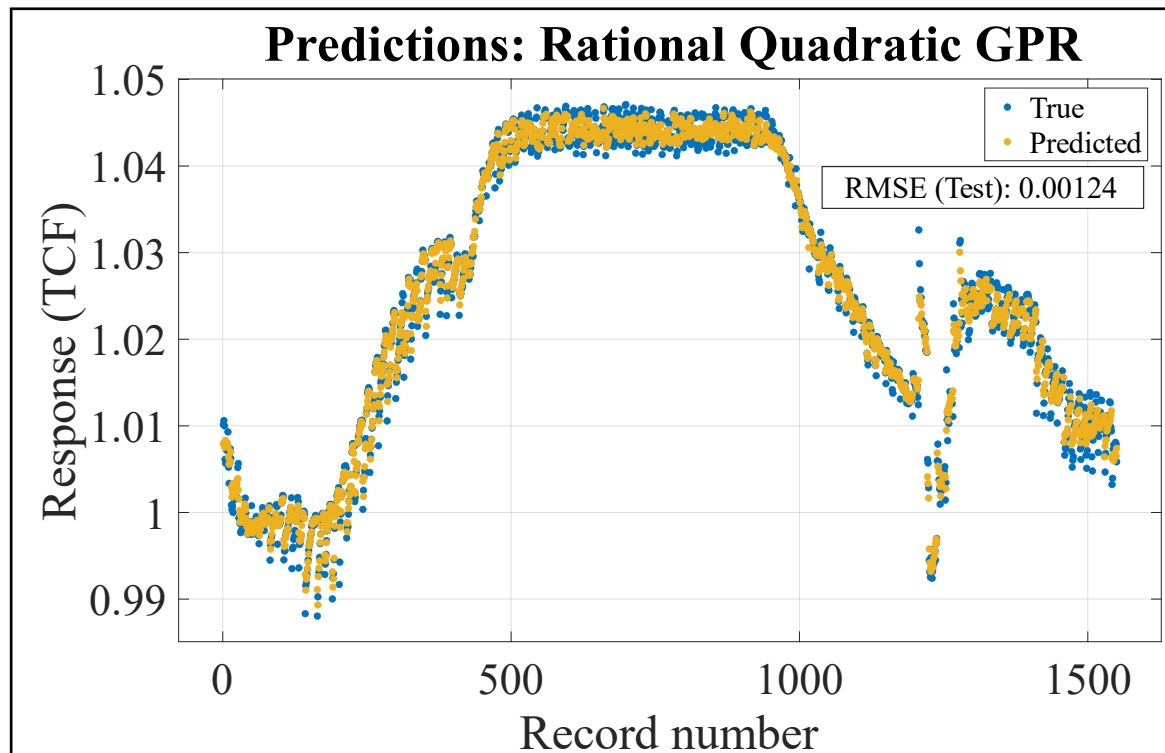
	Model Type	RMSE (Test)
15	Neural Network (<i>Narrow Neural Network</i>)	0.00428
16	SVM (<i>Coarse Gaussian SVM</i>)	0.00461
17	Kernel (<i>Least Squares Regression Kernel</i>)	0.00545
18	Kernel (<i>SVM Kernel</i>)	0.00579
19	Linear Regression (<i>Interactions Linear</i>)	0.00595
20	Stepwise Linear Regression (<i>Stepwise Linear</i>)	0.00596
21	Linear Regression (<i>Linear</i>)	0.00620
22	SVM (<i>Linear SVM</i>)	0.00626
23	Linear Regression (<i>Robust Linear</i>)	0.00634
24	SVM (<i>Quadratic SVM</i>)	0.00760
25	Efficient Linear (<i>Efficient Linear Least Squares</i>)	0.01591
26	Efficient Linear (<i>Efficient Linear SVM</i>)	0.01822
27	Ensemble (<i>Boosted Trees</i>)	0.04358
28	SVM (<i>Cubic SVM</i>)	0.93369



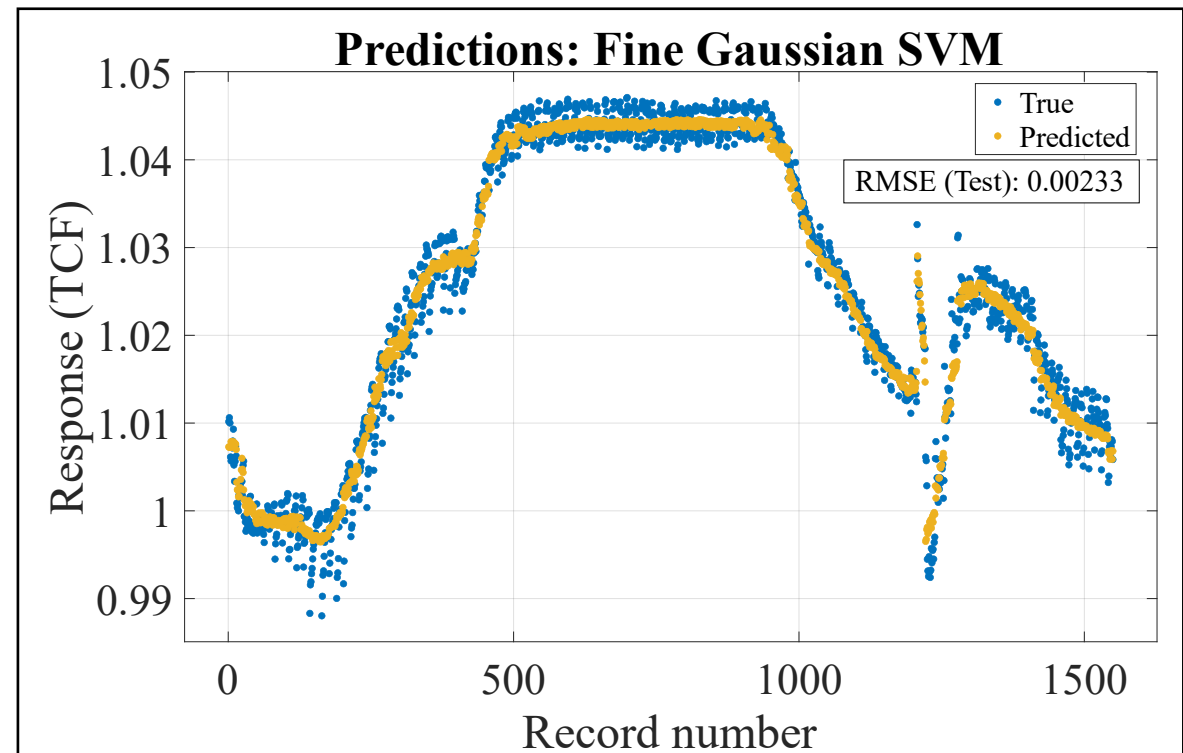
RMSE: Root Mean Squared Error

ML Model Response Plots

Overfit model example



Selected model





TTCF Comparison

$$TOF_{bondline} = TOF_{laminates} - \mathbf{TTCF} \times (TOF_{0,top\ panel} + TOF_{0,bottom\ panel})$$

❖ Scan 62, Time: 170 Minutes, Temperature: 119.4°C

$$TOF_{laminates} = 5.103\mu s$$

$$TOF_{0,top\ panel} = 3.340\mu s$$

$$TOF_{0,bottom\ panel} = 0.832\mu s$$

$$TTCF_{\text{previous Calibration}} = 1.071$$

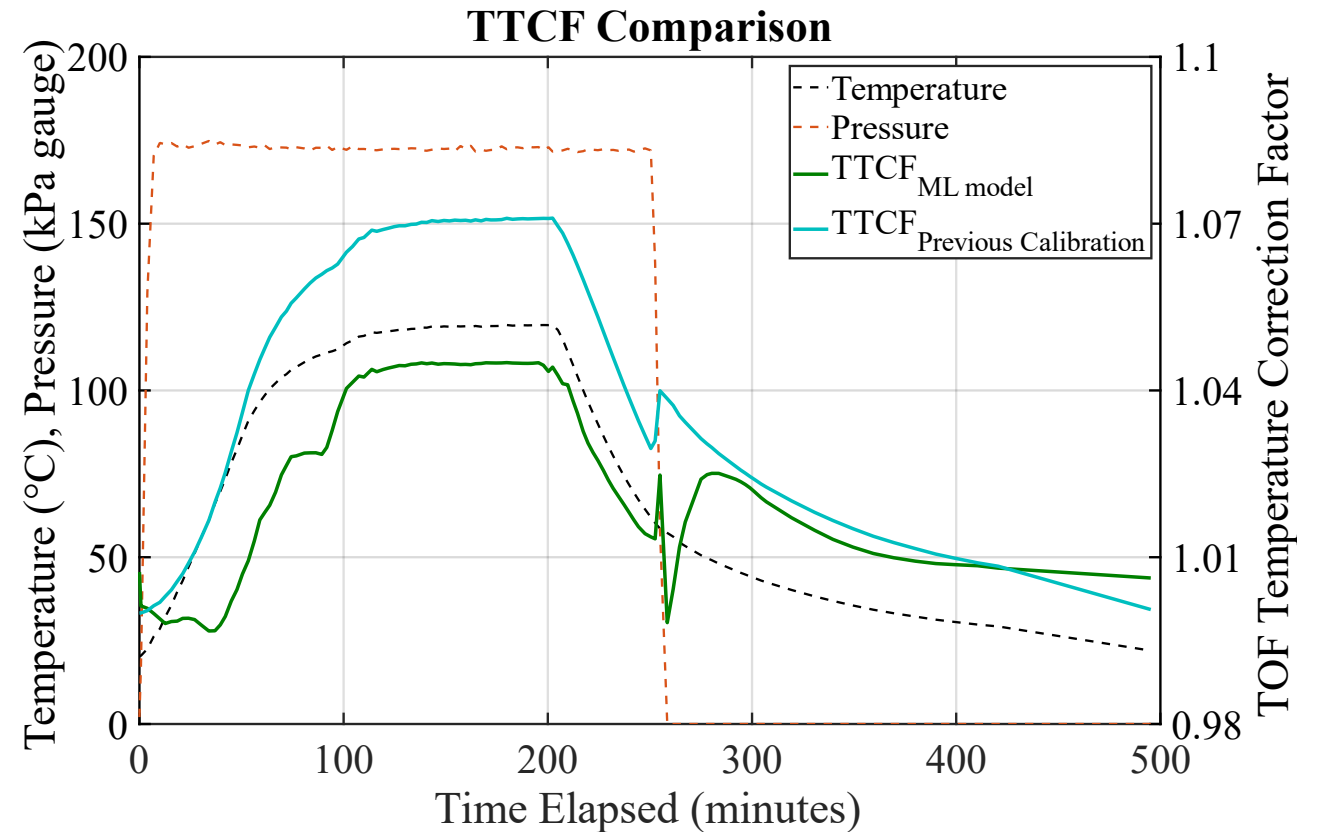
$$TTCF_{\text{ML model}} = 1.045$$

$$\%error, TTCF = 2.47\%$$

$$TOF_{bondline, \text{previous}} = 0.6364\mu s$$

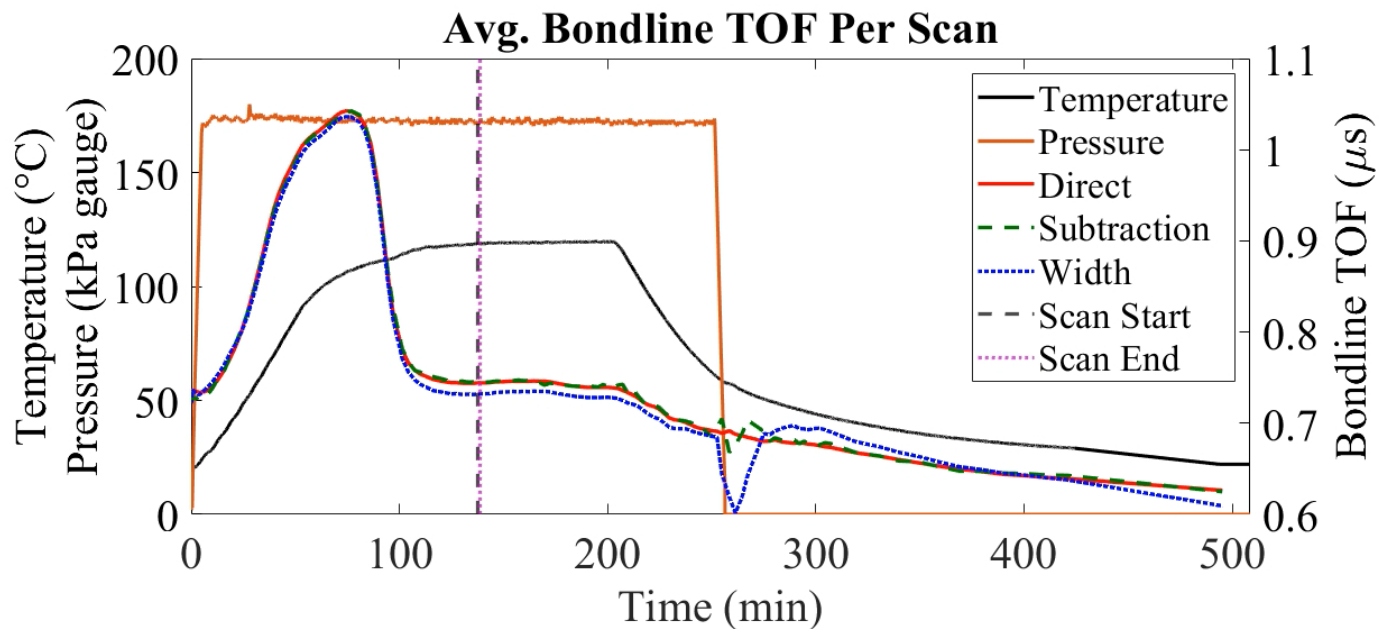
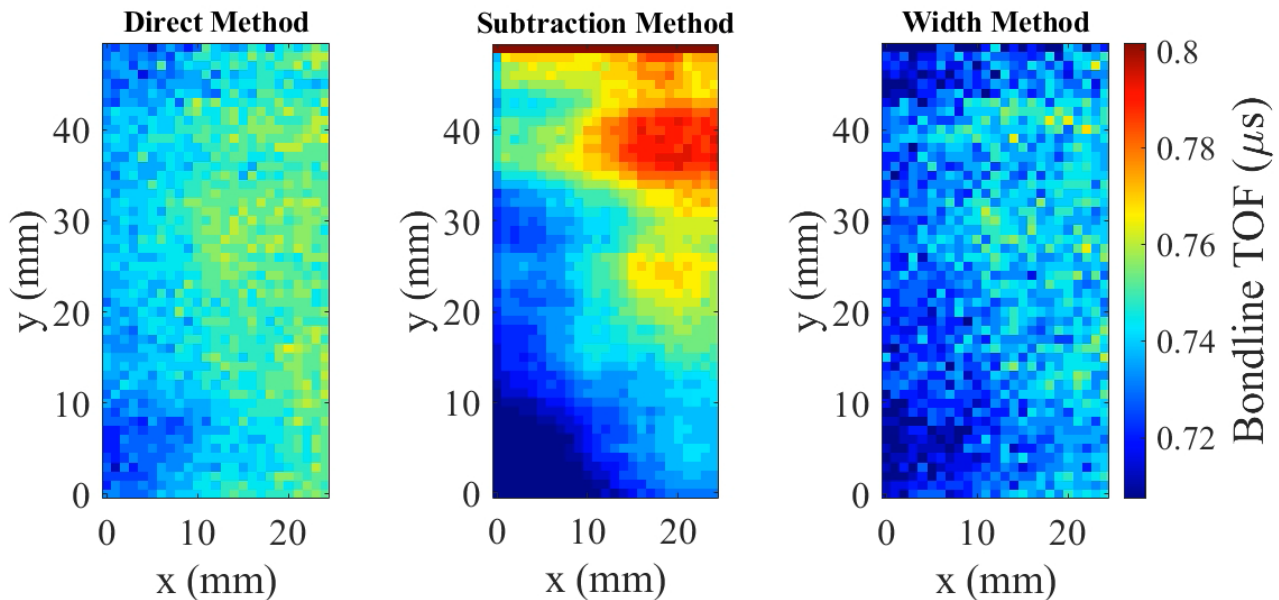
$$TOF_{bondline, \text{ML}} = 0.7440\mu s$$

$$\%error, TOF = 14.46\%$$



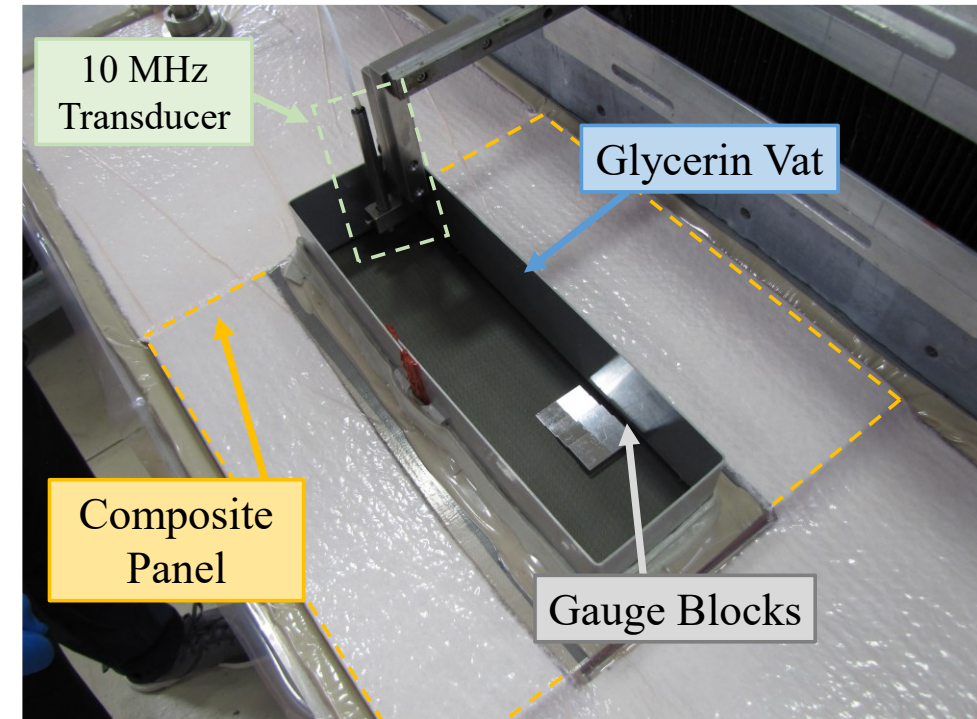
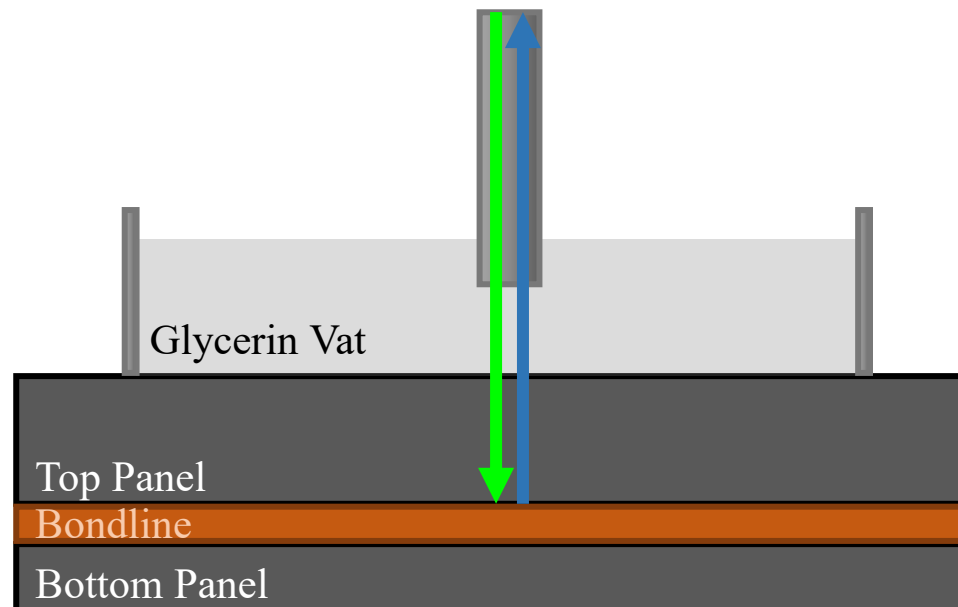


Scan: 50, Time: 137.5-138.8 minutes, Temperature: 118.8-118.9°C

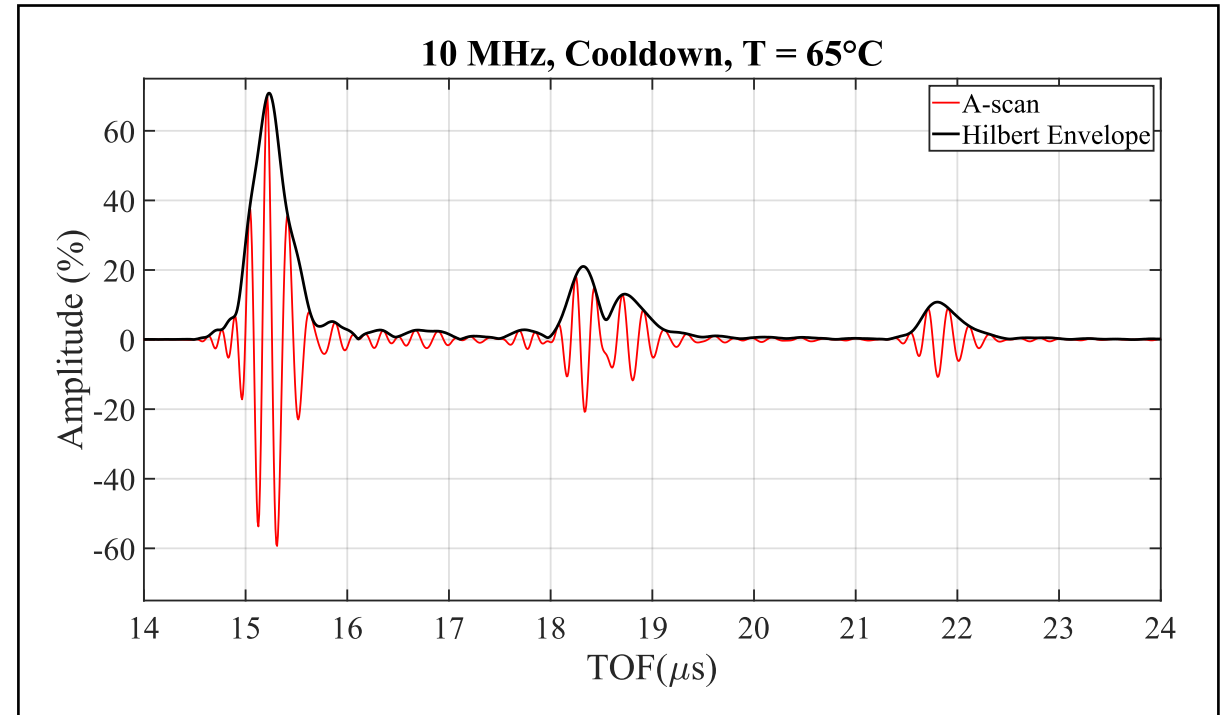
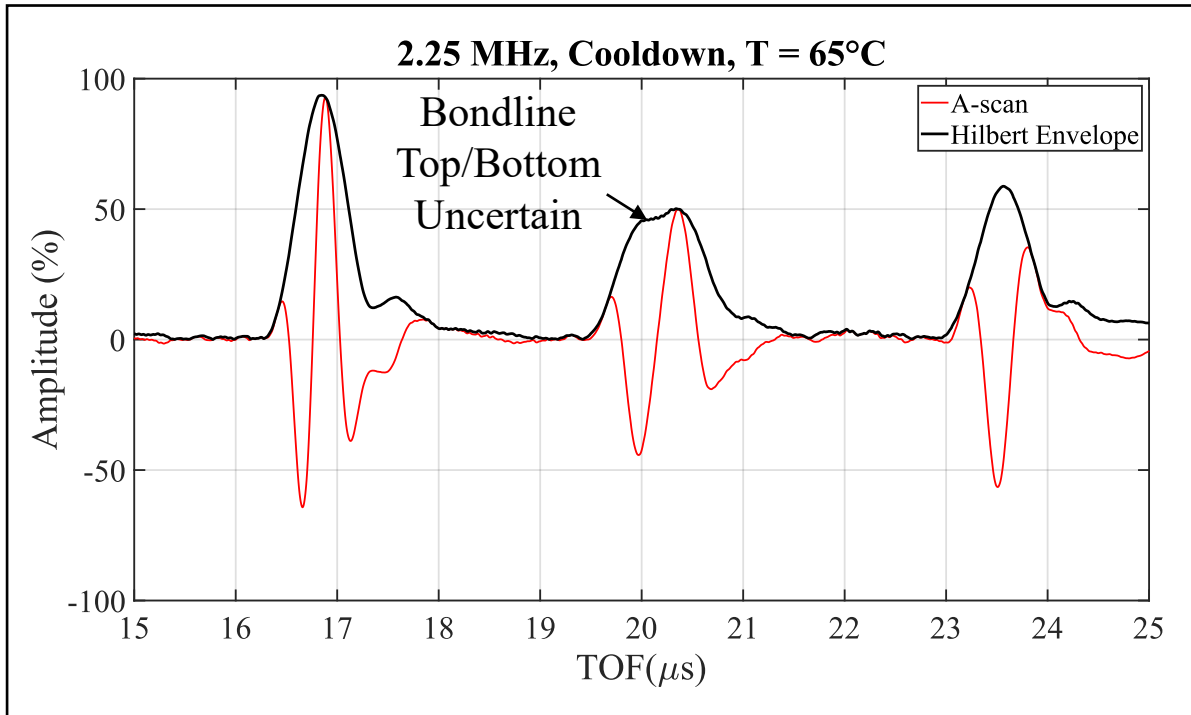


10 MHz Transducer Upgrade

- ❖ 10 MHz immersion probe installed replacing 2.25 MHz contact probe
- ❖ Allows for the direct method on thinner bondlines
 - ❖ Previously limited by the 2.25 MHz probe



10 MHz Transducer Upgrade





Summary

	Direct Method	Subtraction Method	Width Method
Pros	<ul style="list-style-type: none">• No calibration required• Only dependent on top/bottom of bondline peaks	<ul style="list-style-type: none">• Does not require bondline peaks• Easiest peak detection (top/bottom of panel)	<ul style="list-style-type: none">• No calibration required• Available without bondline peaks
Cons	<ul style="list-style-type: none">• Requires clear top/bottom of bondline peaks<ul style="list-style-type: none">• Needs higher frequency transducer for thinner bondlines	<ul style="list-style-type: none">• TTCF calibration required	<ul style="list-style-type: none">• Requires clean front wall peak• Ignores wave dispersion<ul style="list-style-type: none">• Over prediction• Top/bottom of bondline need relatively same magnitude



Acknowledgements

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